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IN : TAKAHASHI IKUO
ISHII HIROMITSU
FUJIWARA TAKESHI

PA : SHARP CORP

TI : FLIP CHIP BONDING

AB : PURPOSE: To avoid defective connections caused by defective soldering by a method wherein, before a semiconductor chip on which solder bumps are formed is mounted on a board, solder flux is applied to the chip so as to cover all the solder bumps beforehand.

CONSTITUTION: Solder bumps 1 are formed on an IC chip 2. The IC chip 2 is so mounted on a board 4 as to have the solder bumps 1 aligned with electrodes 5 formed on the board 4. At that time, solder flux 3 is applied to the IC chip 2 so as to cover all the solder bumps 1 beforehand. The solder flux 3 is made to reflow while it wets both the solder bumps 1 and the electrodes 5 on the board 4. The solder bumps 1 are melted and connected to the electrodes 5 on the board 4. With this constitution, defective connections caused by defective soldering can be avoided.

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